

## **Product / Process Change Notice**

No.: <u>Z200-PCN-DM202407-0</u>2-A Date: July 31, 2024

Change Title: 1Gb (64Mb x16 and 128Mb x8) DDR3/DDR3L technology migration from 25nm to 20nm.						<u> 20nm.</u>		
Change Classification: ☑ Major ☐ Minor change with customer special request ☐ Minor with customer notification Change item : ☐ DataSheet ☑ Design ☐ Raw Material ☐ Wafer FAB ☐ Assembly ☐ Testing ☐ Packing ☐ Manufacture site ☐ Others								
Affected Product(s):	Affected Product(s):							
Please refer to Table 1 in details.								
Description of Change(s)	Description of Change(s)							
Technology migration (25nm to 20nm) for 1Gb DDR3/DDR3L.								
Reason for Change(s):								
According to Winbond product roadmap, launch new 1Gb DDR3/DDR3L with 20nm technology.								
Impact of Change(s) : ( positive & negative )								
Form: No Change								
Fit: No Change (Please refer to attachment I)								
Function: No Concern (Compatible between 25nm and 20nm, refer to attachment II)								
Reliability: No Concern (	Please refer to a	ttachment III)						
Hazardous Substances: No Concern (Please refer to attachment IV)								
Qualification Plan/ Results :								
Based on Winbond EV data result and industrial-plus reliability report, the new product meets our criteria and no quality concern.								
Implementation Plan :								
The follow-up disposition of 25nm 64Mb x16 DDR3/DDR3L and 128Mb x8 DDR3/DDR3L:								
1) The date of last-buy orders: January 31, 2025.								
2) The last shipment date: April 30, 2025.								
□ Date Code: onwar	d 🗖 Lot No:	onward	✓ Propose	ed first ship o	date: October 31	<u>, 2024</u>		
Originator: HYHuang (QA)	Approval: (QA Dept. Manager)	PCChou	Approval: (QRA Director)	TMKuo	Approval: (Quality Center VICE PRESIDENT)	JFTsai		
Contact for Questions & Concerns  Name: Betty Huang TEL:886-3-5678168 (ext.76549) FAX: 886-3-5796124  Address: No. 8,Keya 1st Rd., Daya Dist., Central Taiwan Science Park, Taichung City 42881,Taiwan  E-mail: Hyhuang8@winbond.com								
Impact of Change(s): (positive & negative) Form: No Change Fit: No Change (Please refer to attachment I) Function: No Concern (Compatible between 25nm and 20nm, refer to attachment II) Reliability: No Concern (Please refer to attachment III) Hazardous Substances: No Concern (Please refer to attachment IV)  Qualification Plan/ Results: Based on Winbond EV data result and industrial-plus reliability report, the new product meets our criteria and no quality concern.  Implementation Plan: The follow-up disposition of 25nm 64Mb x16 DDR3/DDR3L and 128Mb x8 DDR3/DDR3L: 1) The date of last-buy orders: January 31, 2025. 2) The last shipment date: April 30, 2025. □ Date Code: onward □ Lot No: onward ☑ Proposed first ship date: October 31, 2024  Originator: (QA) Dept. (QA Dept. (QAA Director) Wanager)  Name: Betty Huang TEL:886-3-5678168 (ext.76549) FAX: 886-3-5796124 Address: No. 8, Keya 1st Rd., Daya Dist., Central Taiwan Science Park, Taichung						JFTsai -5796124		

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## **Customer Comments:**

Note: Please sign this notice, and return to Winbond contact within **30** days. If no response is received within **30** days, this Change Request will be assumed to meet your approval.

Major change: □ Approval			roval:					
Minor with customer special re	<i>quest:</i> □ Approval	■ Disapproval	☐ Conditional Approval :					
Minor change with customer notification: □ Recognition								
Comment:								
Date:								
Dept. name:								
Person in charge:								

Table No.: 1110-0001-08-A

## **Esses winbond**

## Table 1. The affected part no is listed below.

W631GG6NB-09	W631GG6NB09I	W631GG6NB09J	W631GG6NB-11	W631GG6NB11I
W631GG6NB11J	W631GG6NB-12	W631GG6NB12I	W631GG6NB12J	W631GG6NB-15
W631GG6NB15I	W631GG6NB15J	W631GU6NB-09	W631GU6NB09I	W631GU6NB-11
W631GU6NB11I	W631GU6NB11J	W631GU6NB-12	W631GU6NB12I	W631GU6NB12J
W631GU6NB-15	W631GU6NB15I	W631GG8NB-09	W631GG8NB09I	W631GG8NB09J
W631GG8NB-11	W631GG8NB11I	W631GG8NB11J	W631GG8NB-12	W631GG8NB12I
W631GG8NB12J	W631GG8NB-15	W631GG8NB15I	W631GG8NB15J	W631GU8NB-09
W631GU8NB09I	W631GU8NB09J	W631GU8NB-11	W631GU8NB11I	W631GU8NB11J
W631GU8NB-12	W631GU8NB12I	W631GU8NB12J	W631GU8NB-15	W631GU8NB15I
W631GU8NB15J				

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